

WAFER POLISHING SYSTEM AND WAFER TRANSFER METHOD

ABSTRACT

5 Disclosed in the present invention is a wafer polishing system, comprising polishing units. Each polishing unit comprises a wafer transfer channel and a polishing module; the polishing module comprises a polishing platform and a polishing arm, and the polishing arm can drive a wafer to move relative to the polishing platform; the wafer transfer channel is provided with at least two work stations, and a wafer loading/unloading table can move between the work stations;

10 a transmission structure is provided between adjacent polishing units, a wafer is transferred between work stations of the adjacent polishing units along a first track, and the first track falls on wafer transfer channels; and/or a wafer loading/unloading table can move between adjacent polishing units; and/or a transfer structure is provided between a polishing unit and an external transition table, a wafer is transferred between work stations of the polishing unit and the external

15 transition table along a second track, and the second track falls on a wafer transfer channel. Further disclosed in the present invention is a wafer transfer method. In the present invention, tracks all fall on wafer transfer channels, so that no other space is occupied, and the layout is reasonable; the process is flexible, and the processing efficiency is high; the transfer stability is high.

20 FIG. 1-1